

Appl. No. 10/707,824
Amdt. dated August 12, 2005
Reply to Office action of May 13, 2005

Listing of Claims:

1. (original)A method of defect review comprising following steps:
providing a wafer with a plurality of defects;
performing a defect inspection to detect the defects;
5 performing an automatic defect classification according to a database to separate the
defects into a plurality of defect types; and
performing a defect review;
wherein each defect type has different sampling ratios in the defect review according
to its influence degree of process yield.
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2. (original)The method of claim 1 wherein the database comprises information about
the plurality of defect types and defect information corresponding to each defect type.
3. (original)The method of claim 2 wherein the defect information comprises the
15 influence degree of the process yield of each defect type.
4. (original)The method of claim 3 wherein the database separates the defect types into
killer defects and non-killer defects according to the influence degree of the process yield.
- 20 5. (original)The method of claim 4 wherein the sampling ratio of the killer defects in
the defect review is larger than that of the non-killer defects.
6. (original)The method of claim 3 wherein the database separates the defects into
pre-layer defects and adding defects, and further separates the adding defects into killer
25 defects and non-killer defects.
7. (original)The method of claim 6 wherein the defect review focuses on the adding

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defects.

8. (original)The method of claim 1 wherein after finishing the defect inspection, a judgment of cluster defects is performed and a defect review with a high sampling ratio is
- 5 performed on the cluster defects if the cluster defects exist.
9. (original)The method of claim 1 wherein the database is updated according to the result of the defect review after finishing the defect review.

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